

## PIC05018Q TYPE

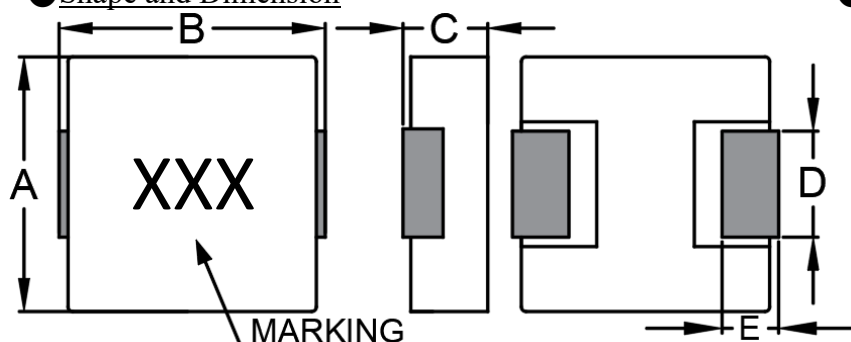
### ●FEATURE

1. Shielded construction
2. Alloy metal material used, Low DCR ,Low Buzz Noise
3. AEC-Q200 Qualified

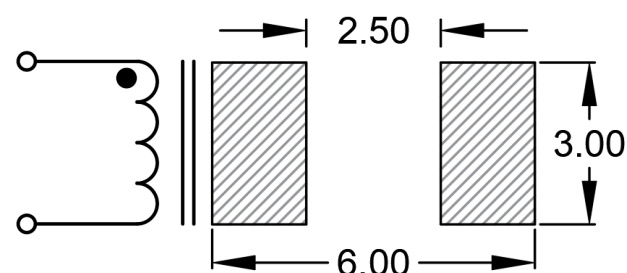
### ●Applications

1. Notebook, server application, High current power supplier

### ●Shape and Dimension



### ●Schematics and Land Patterns(mm)



A=5.40mm Max. ; B=5.70mm Max. ; C=1.80mm Max. ; D=2.20±0.30mm ; E=1.20mm Ref.

### ●Specification

P/N	L (uH)	RDC (mΩ) Typ.	RDC (mΩ) Max.	Isat (A)	Irms (A)
PIC05018Q-R47M	0.47±20%	1.7	9.0	15.5	11.5
PIC05018Q-R56M	0.56±20%	8.0	10.0	15.0	10.5
PIC05018Q-1R0M	1.00±20%	15.0	17.0	9.0	8.5
PIC05018Q-2R2M	2.20±20%	30.0	35.0	6.5	5.5
PIC05018Q-3R3M	3.30±20%	52.0	58.0	5.0	4.5
PIC05018Q-4R7M	4.70±20%	78.0	85.0	4.0	3.5
PIC05018Q-6R8M	6.80±20%	107.0	120.0	3.4	2.8
PIC05018Q-100M	10.0±20%	140.0	155.0	3.0	2.5

Note1. Measurement frequency of Inductance value : at 100kHz, 1.0V

Note2. Measurement ambient temperature of L, DCR and IDC : at 25°C

Note3. Isat: DC current at which the inductance drops 30%(Typ.) from its value without current

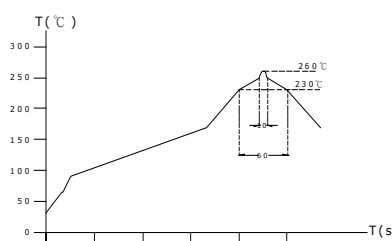
Note4. Irms: Average current for 40°C temperature rise from 25°C ambient(Typ.)

Note5. Packaging: Taping ; Quantity: 2000 Pieces/Reel

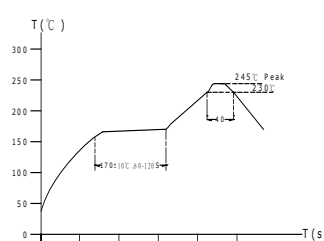
## GENERAL CHARACTERISTICS

1. Operating temperature range: -55 TO + 155°C (Includes temperature when the coil is heated)
2. High temperature exposure(storage) refer MIL-STD-202 Method 108: 1000 hrs at rated operating temperature(e.g. 155°C). Part can be stored for 1000 hrs @155°C. Unpowered. Measurement at 24±4 hours after test conclusion.
3. Temperature cycling refer JESD22 Method JA-104: 1000 cycles(-55 TO + 155°C). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temp. extreme. 1 min. maximum transition time.
4. Biased Humidity refer MIL-STD-202 Method 103: 1000 hours 85°C/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.
5. Operational Life refer MIL-PRF-27: 1000 hrs. at 155 °C tested. Measurement at 24±4 hours after test conclusion.
6. External Visual refer MIL-STD-883 Method 2009: Inspect device construction, marking and workmanship.
7. Physical Dimension refer JESD22 Method JB-100: Verify physical dimensions to the applicable device detail specification.
8. Resistance to Solvents refer MIL-STD-202 Method 215: Add aqueous wash chemical - OKEM clean or equivalent.
9. Mechanical Shock refer MIL-STD-202 Method 213: Figure 1 of Method 213. Condition C.
10. Vibration refer MIL-STD-202 Method 204: 5g;s for 20 minutes, 12 cycles each of 3 orientations. Test from 10-2000 Hz.
11. Resistance to soldering Heat refer MIL-STD-202 Method 210: Condition B No pre-heat of samples. Single wave solder-procedure 2 for SMD and procedure 1 for leaded with solder within 1.5mm of device body.
12. ESD refer AEC-Q200-002 or ISO/DIS 10605: Direct contact discharge 2kV.
13. Solderability refer J-STD-002: For both Leaded & SMD. Magnification 50X. Conditions: Leaded, Method A@235°C, category 3 ; SMD, a)Method B, 4hrs@155°C dry heat @235°C, b)Method B@215°C category 3., c)Method D category 3@260°C
14. Electrical Characterization refer spec: Show Min, Max Mean and Standard deviation at room from Min and Max temperature.
15. Flammability refer UL-94: V-0 or V-1 Acceptable.
16. Board Flex refer AEC-Q200-005: 60 sec minimum holding time.
17. Terminal Strength(SMD) refer AEC-Q200-006
18. Reflow profile recommend:

Lead-free heat endurance test



Lead-free the recommended reflow condition



*You are the winner*

● Typical Electrical Curve: Inductance VS Isat , Irms VS TEMP.

